

QUALIFICATIONS

The solder paste BLF 02 is an RMA-paste that accords to the requirements of the MIL-QQ-S571e. The corrosion-, solderball- and the wetting test as well as the slump (according to ISO, J-STD-004/005 L1) were passed. Laboratory research confirmed corrosion free residues, corresponding to the RE-L0, which can remain on the board.

HANDLING

After taking out the paste, close the container tightly. Used paste should not be stored with fresh paste together. In the running working process it is of course allowed to mix in fresh paste to freshen up the old one. Different alloys and types of paste shall not be mixed.

Recommended squeegee speed: 15 – 100 mm/s.

Remember! The printer is always faster than the fastest assembler in the line. The most important is that the paste rolls in front of the squeegee.

For stencil printing a paste with 89% metal content is recommended.

The cleaning of the stencil can be done with an alcoholic mixture, but the cleaning medium shall under no circumstances get in contact with the paste. **We recommend thus the SC Stencilcleaner.** The solder paste is applicable with all common reflow systems.

STORAGE

Unopened at room temperature (20°C/68°F): 6 months

Opened or at the squeegee of the printing device the maximum working time is dependant of the environmental influences to which the paste is exposed. **A storage in the refrigerator is not necessary!**

Solder Chemistry order example

Paste	Alloy	Grain size	Flux content	Jar capacity
SC BLF 02	96.5/3.0Ag/0.5Cu	T3	11%	500g
SC BLF 02	96.5/3.5Ag	T3	11%	500g

Order example according to DIN:

Solder Paste (SC...) L-Sn96.5/Ag3/Cu0.5 / F-SW 32 / 89 - 3 500g (packing)

Solder Chemistry ; Fragnerstrasse 4 ; D-84034 Landshut
Tel. ++49/871/4309500 ; Fax. ++49/871/43095020
e-Mail: info@SolderChemistry.com ; www.SolderChemistry.com

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